## OR PATENT APPLICATION (WITH POWER O.



As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR TRANSFER MOLDING ENCAPSULATION OF A SEMICONDUCTOR DIE WITH ATTACHED HEAT SINK, the specification of which (check one):

⊠ is attached hereto.  □ was filed on as Unit	ted States application serial no.	and was amended on .		
		nd was amended under PCT Article 19 on	···········•	
I hereby state that I have reviewed and referred to above.	d understand the contents of the above-identi	ified specification, including the claims, as amend	ied by any am	endment.
Lecknowledge the duty to disclose to	the U.S. Patent and Trademark Office all in	formation known to me to be material to the pate	entability of the	e subject
	steriality" is defined in Title 37, Code of Fed		induity of the	s autijeet
•				
		(a)-(d) or § 365(b) of any foreign application(s) f	. *	
• • • • •	• • •	country other than the United States of America		
• •	<del>-</del>	istion page any foreign application for patent or i nited States of America having a filing date befor		meate or
application(s) on which priority is claimed	•	med States of Afficient having a limit date better	io mac or me	
Sure Sura				
Prior foreign/PCT application(s):				
			Priority C	laimed
(ausalia a)	(country)	(day/month/year filed)	Yes	No
(number)	•		* 4	
(austina)	(country) ·	(day/month/year filed)	Yes	No
5 E.B	<del>-</del>	States application(s) or § 365(c) of PCT internat		
designating the United States of America	listed below and on any attached continuatio	on page and, insofar as the subject matter of each	of the claims	of this
annification is not disclosed in any such no	ior annication in the manner provided by th	e first paragraph of Title 35, United States Code	8 112 Lack	nowledge
	**	o me to be material to patentability as defined in		
		ication and the national or PCT international filin	•	
en e	to retire of the first approximation of the price approximation of the pric		g date of this	apprication
*				
(application serial no.)	(filing date)	(status - pending, patented or	abandoned)	
242 242				
(application serial no.)	(filing date)	(status - pending, patented or a	abandoned)	
I hereby claim the benefit under Title 3	5, United States Code, § 119(e) of any Unit	ed States provisional application(s) listed below:		
-	•			
(provisional application no.)	(filing date)	<del></del>		
dionicial approaches not	(ming date)			
(provisional application no.)	(filing date)			
(movisional application no.)	(ining date)			
(provisional application no.)	(filing date)	<del> </del>		
I hereby appoint the following Register connected therewith:	red Practitioners to prosecute this application	n and to transact all business in the Patent and Tr	ademark Offic	:e
David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969	Thomas J. Rossa, Reg. No. 26,799		
Laurence B. Bond, Reg. No. 30,549	Joseph A. Walkowski, Reg. No. 28,76			
Allen C. Turner, Reg. No. 33,041	Kent S. Burningham, Reg. No. 30,453	Julie K. Morriss, Reg. No. 33,263		
Robert G. Winkle, Reg. No. 37,474	Patrick McBride, Reg. No. 39,295	Edgar R. Cataxinos, Reg. No. 39,931		
Michael L. Lynch, Reg. No. 30,871	Lia M. Pappas, Reg. No. 34,095	,		
Address all correspondence to:	James R. Duzan, telephone no. (801) 532-1	ດວາ		
•	TRASK, BRITT & ROSSA	922.		
	P.O. BOX 2550			
	Salt Lake City, Utah 84110			
	Same Only, Class 194110			
I hereby declare that all statements ma-	de herein of my own knowledge are true an	d that all statements made on information and be	lief are believe	ed to be
true; and further that these statements wer	re made with the knowledge that willful falso	e statements and the like so made are punishable	by fine or imp	risonment
		il false statements may jeopardize the validity of		

Williams ( Date 2-21-97

Residence: Boise, Idaho Citizenship: U.S.A.

Full name of sole inventor: Richard W. Wensel

patent issued thereon.

Inventor's signature

Post Office Address: 2358 Wyoming Avenue, Boise, Idaho 83706